	C Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1					Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infor					fg Informati	on	
upplie	r Information													
Company name* Company unique ID						Unique ID Authority					Response Date*			
nsemi											2024-05	-17		
Contact N	lame		Title - Contact				Phone - Contact*			Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Repre	itle - Representative Phone - Representative*				Email - Representative*						
roduct-I	Env-Stewards		Product Envi	ro Compliance			NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number	Mfr Item Name			Effective Date	Version	Ma	nufacturing Site	Weight* UOM Un		Unit Type	
		STK531	U394A-E	Inverter			2024-05-17		VN	12		14100.0	mg	Each
Ianufa	cturing Proccess Informa	tion												
Terminal Plating / Grid Array Material		Terminal Base	Alloy	J-STD-020 MS	STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature		ture Numb	er of Reflow Cyc	cles					
	Matte Tin (Sn) - annealed	C	CU Alloy		NA		0		С	30	secor	nds 3		
omments	3													
or more i	information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to ha			ice drop-dowi	n. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature R	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip Parts	48.77	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.2778	mg
			Supplier	Silver (Ag)	7440-22-4		1.2095	mg
			Supplier	Epoxy resins	129915-35-1		0.4097	mg
			Supplier	Tin (Sn)	7440-31-5		1.3314	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0878	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.834	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		6.6474	mg
			Supplier	Phenolic resins	Proprietary Data		0.0585	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0195	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		30.5203	mg
			В	Nickel (Ni)	7440-02-0		3.0335	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.0585	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0049	mg
			Supplier	Copper (Cu)	7440-50-8		2.8726	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.4048	mg
Die	33.44	mg	Supplier	Silicon (Si)	7440-21-3		33.44	mg
Die Attach	2.03	mg	Supplier	Silver (Ag)	7440-22-4		1.4642	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.3536	mg
			Supplier	Tin (Sn)	7440-31-5		0.1192	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0818	mg
			В	Antimony (Sb)	7440-36-0		0.0112	mg
Ieat Sink	864.0	mg	Supplier	Silver (Ag)	7440-22-4		138.24	mg
			Supplier	Copper (Cu)	7440-50-8		725.7599	mg
lead Frame	523.74	mg	Supplier	Tin (Sn)	7440-31-5		0.3142	mg
			Supplier	Copper (Cu)	7440-50-8		523.4257	mg
Iold Compound-Black	8485.29	mg		Brominated epoxy resin	proprietary data		21.2132	mg
			Supplier	Phenolic Resin	Proprietary Data		439.538	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		15.2735	mg
			Supplier	Carbon Black (C)	1333-86-4		34.7897	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		594.8188	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5573.1387	mg

			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	934.2305	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	872.2878	mg
Plating	1.05	mg	Supplier	Tin (Sn)	7440-31-5	0.6499	mg
			В	Nickel (Ni)	7440-02-0	0.4	mg
RDL	3991.0		В	Nickel (Ni)	7440-02-0	2470.429	mg
			Supplier	Gold (Au)	7440-57-5	21.5514	mg
			Supplier	Copper (Cu)	7440-50-8	7.5829	mg
			Supplier	Aluminum (Al)	7429-90-5	1491.4366	mg
Solder Ball	77.8		Supplier	Silver (Ag)	7440-22-4	2.1706	mg
			Supplier	Tin (Sn)	7440-31-5	75.1704	mg
			В	Antimony (Sb)	7440-36-0	0.07	mg
			Supplier	Copper (Cu)	7440-50-8	0.389	mg
Wire Bond	72.88		Supplier	Silicon (Si)	7440-21-3	0.0073	mg
			Supplier	Aluminum (Al)	7429-90-5	72.8727	mg